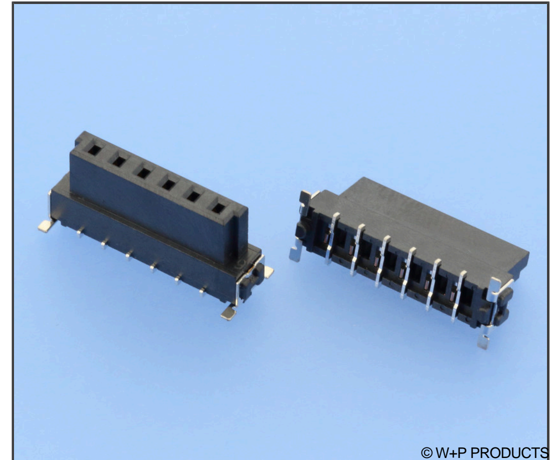
9028

SMT-Buchsenleiste RM 2,54mm, stehend

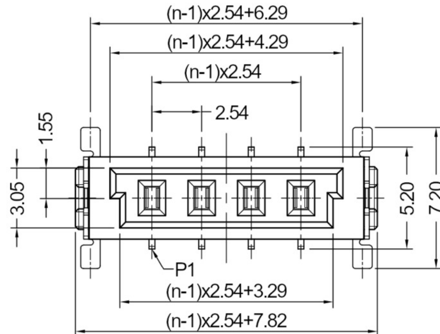
SMT Female Connector 2,54mm Pitch, vertical

Technische Daten / *Technical Data*

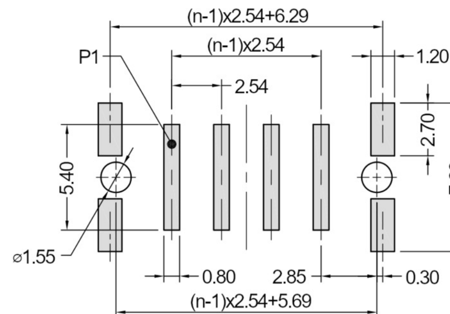
Isolierkörper	Thermoplast, nach UL94 V-0
Insulator	*Thermoplastic, rated UL94 V-0*
Kontaktmaterial	Kupferlegierung
Contact Material	*Copper alloy*
Kontaktoberfläche	Lt. Oberflächenoptionen, über Ni
Contact Surface	*Acc. to plating options, over Ni*
Durchgangswiderstand	< 10 mΩ
Contact Resistance	*< 10 mΩ*
Isolationswiderstand	> 10000 MΩ
Insulation Resistance	*> 10000 MΩ*
Spannungsfestigkeit	1390 V AC
Test Voltage	*1390 V AC*
Nennspannung	180 V AC/DC Max.
Voltage Rating	*180 V AC/DC Max.*
Nennstrom	Siehe Tabelle unten
Current Rating	*According to table below*
Temperaturbereich	-55 °C ... +125 °C
Temperature Range	*-55 °C ... +125 °C*
Verarbeitung	Reflow-Lötverfahren 260 °C / 10 sec. max.
Processing	*Reflow soldering 260 °C / 10 sec. max.*

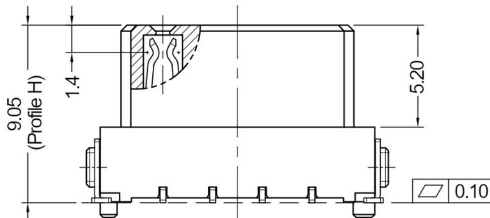


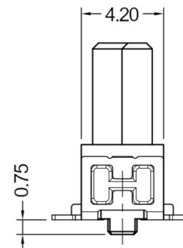
Gegenstecker / *Mating Connectors*:
9029 9030

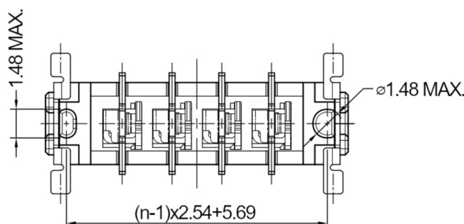


Recommended P.C.B Layout (Top Side)
(PCB BOARD TOLERANCE±0.05)









Series	*Contacts**	*Profile*	*Plating**	*Packing*
9028	**04**	**2**	**60**	**PPTR**
	02/03/04/05/06/12	**2** H=9.05mm	**60** Sel. Au flash / Sn over Ni **80** Sel. Au 30µ" / Sn over Ni	**PPTR** Tape & Reel mit Pick&Place-Pads *Tape & Reel with Pick&Place-Pads*

* Dies ist ein **Bestellbeispiel** -
bitte durch Ihre Spezifikationen ersetzen.
** This is an **order example** -*
please replace by your specifications.

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9027 9028 9029 9030

Nennströme und Bauhöhen

Current Ratings and Mating Heights

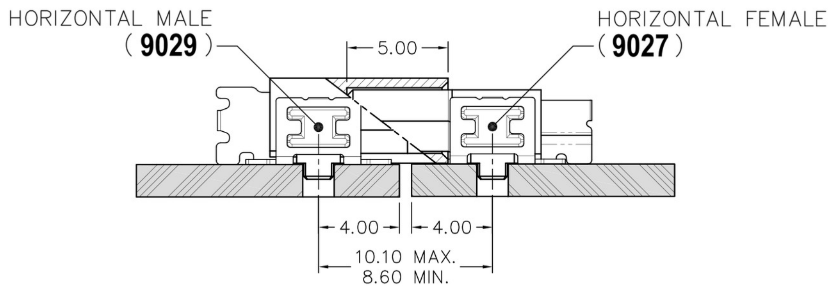
Nennströme in Abhängigkeit von Polzahl und Gegenstecker

Current Ratings in accordance to Contact Number and Mating Connector

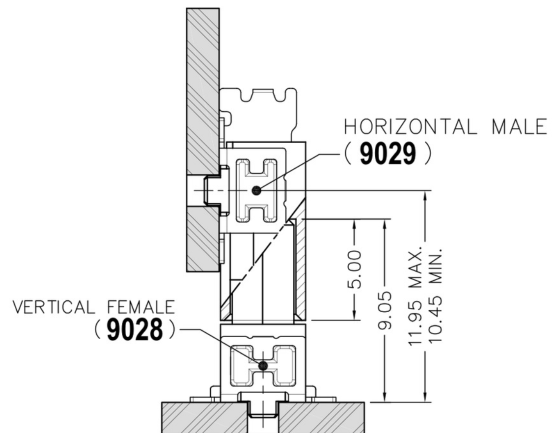
Mating Pair	2 Contacts	3~6 Contacts	12 Contacts
9027-2029	21 A max.	15 A max.	12 A max.
9028-9029	19 A max.	13 A max.	10 A max.
9027-9030	19 A max.	13 A max.	10 A max.
9028-9030	19 A max.	13 A max.	10 A max.

Bauhöhendiagramme

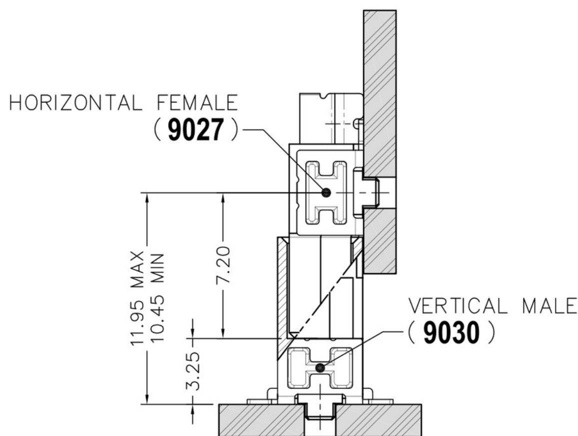
Diagrams of Mating Pairs



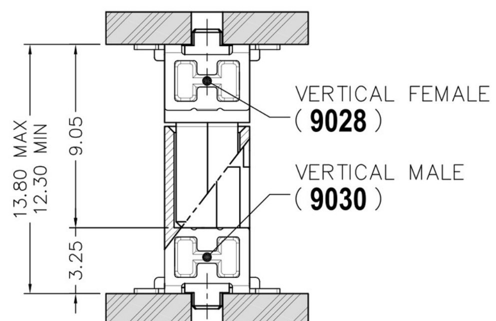
Mating Application - Extender Card



Mating Application - Daughter Card to Motherboard



Mating Application - Daugher Card



Mating Application - Board to Board Stacking

Design- und technische Änderungen auch ohne vorherige Ankündigung vorbehalten.

Design and/or technical specifications may change without prior notice.

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Reflow-Lötempfehlung für kurze Lötzeiten

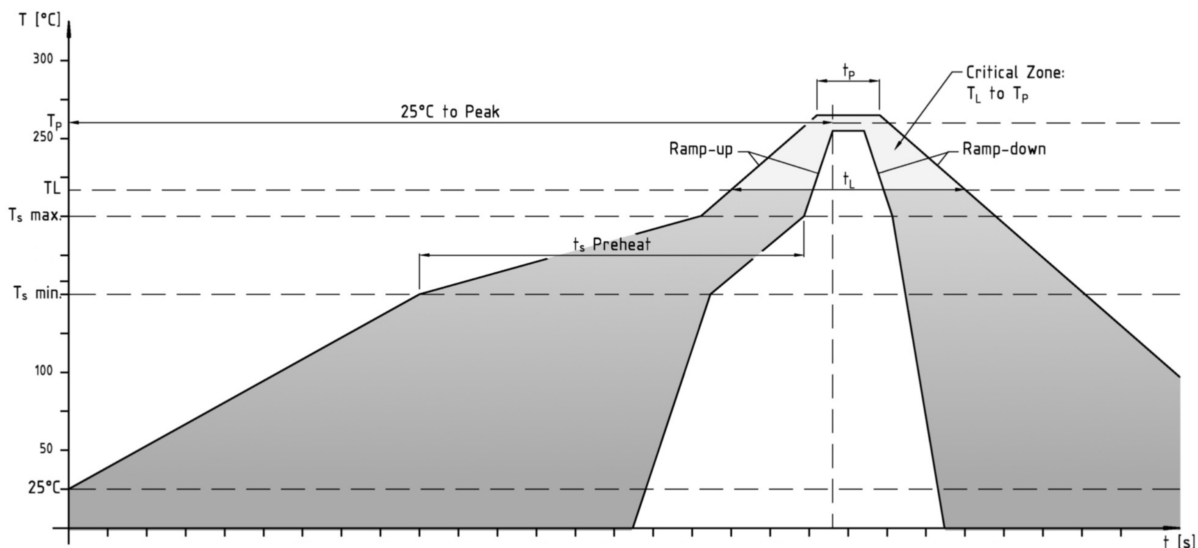
Die Bauteile sollten gemäß folgendem Temperatur-Profil in Anlehnung an die IPC/JEDEC J-STD-020C für bleifreies Löten im Reflow-Verfahren verarbeitet werden (Maximalwerte).

Profileigenschaft	Kennwert
Temperatur Minimum $T_S$min	150°C
Temperatur Maximum $T_S$max	200°C
Dauer $T_S$min - $T_S$max	120-150s
Temperatur Lötbereich T_L	230°C
Verweildauer oberhalb T_L	60s max.
Ramp-Up Rate $T_S$max - T_P	max. 1,5°C / s
Höchsttemperatur T_P	260°C max.
Dauer Höchsttemperatur	5-10s
Ramp-Down Rate $T_P$max - $T_S$min	3°C / s
Dauer 25°C - Höchsttemperatur T_P	Max. 4,5min

Reflow Soldering Recommendation For Shorter Peak Times

Items should be soldered according to IPC/JEDEC J-STD-020C temperature profile for leadfree reflow soldering (maximum values).

Profile Feature	Key Values
Minimum Temperature $T_S$min	*150°C*
Maximum Temperatur $T_S$max	*200°C*
Duration $T_S$min - $T_S$max	*120-150s*
Soldering Range Temperature T_L	*230°C*
Duration above T_L	*60s max.*
Ramp-Up Rate $T_S$max - T_P	*max. 1.5°C / s*
Peak Temperature T_P	*260°C max.*
Duration Peak Temperature	*5-10s*
Ramp-Down Rate $T_P$max - $T_S$min	*3°C / s*
Duration 25°C - Peak Temp. T_P	*Max. 4.5min*



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Design and/or technical specifications may change without prior notice.

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